

### **CLOCK DISTRIBUTION CIRCUIT**

IDT6P30006A

## **Description**

The IDT6P30006A is a low-power, eight output clock distribution circuit. The device takes a TCXO or LVCMOS input and generates eight high-quality outputs.

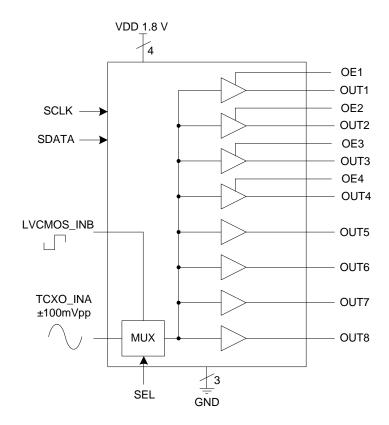
It includes a redundant input with automatic glitch-free switching when the primary reference is removed. The primary input may be selected by the user by pulling the SEL pin low or high. If the primary input is removed and brought back, it will not be re-selected until 1024 cycles have passed.

The IDT6P30006A specifically addresses the needs of handheld applications in both performance and package size. The device is packaged in a small 4mm x 4mm 24-pin QFN, allowing optimal use for limited board space.

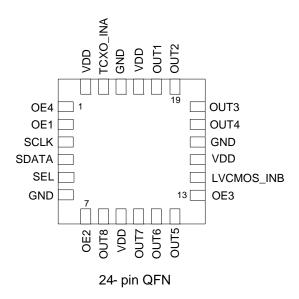
### **Features**

- Packaged in 24-pin QFN
- LVCMOS or TCXO sine wave input
- +1.8 V operating voltage
- · Glitch-free input switching
- Eight buffered square wave outputs at 1.8 V LVCMOS levels
- Individual output enables controlled via I<sup>2</sup>C or OEx
- Pb free, RoHS compliant package
- Industrial temperature range (-40°C to +85°C)

### **Block Diagram**



# **Pin Assignment**



# **SEL Pin Configuration Table**

| SEL | Primary Input |
|-----|---------------|
| 0   | LVCMOS_INB    |
| 1   | TCXO_INA      |

# **OE Pin Configuration Table**

| OEx OUTx |          |  |  |  |
|----------|----------|--|--|--|
| 0        | Disabled |  |  |  |
| 1        | Enabled  |  |  |  |

# **Pin Descriptions**

| Pin<br>Number | Pin<br>Name    | Pin<br>Type | Pin Description   |
|---------------|----------------|-------------|---|
| 1             | OE4            | Input       | Output enable control for OUT4. Internal pull-up resistor. See table above. |
| 2             | OE1            | Input       | Output enable control for OUT1. Internal pull-up resistor. See table above. |
| 3             | SCLK           | Input       | I <sup>2</sup> C clock input.   |
| 4             | SDATA          | I/O         | I <sup>2</sup> C data input.  |
| 5             | SEL            | Input       | Select pin for primary inputs. See table above. Internal pull-up resistor.  |
| 6             | GND            | Power       | Connect to ground.  |
| 7             | OE2            | Input       | Output enable control for OUT2. Internal pull-up resistor. See table above. |
| 8             | OUT8           | Output      | Buffered output. Outputs tri-state with weak pull-down when disabled.       |
| 9             | VDD            | Power       | Connect to +1.8 V.  |
| 10            | OUT7           | Output      | Buffered output. Outputs tri-state with weak pull-down when disabled.       |
| 11            | 11 OUT6 Output |             | Buffered output. Outputs tri-state with weak pull-down when disabled.       |
| 12            | OUT5 Output    |             | Buffered output. Outputs tri-state with weak pull-down when disabled.       |
| 13            | OE3            | Input       | Output enable control for OUT3. Internal pull-up resistor. See table above. |
| 14            | LVCMOS_INB     | Input       | Connect to 13 MHz LVCMOS clock input. See table above.                      |
| 15            | VDD            | Power       | Connect to +1.8 V.  |
| 16            | GND            | Power       | Connect to ground.  |

| Pin<br>Number | Pin<br>Name | Pin<br>Type | Pin Description   |
|---------------|-------------|-------------|---|
| 17            | OUT4        | Output      | Buffered output. Outputs tri-state with weak pull-down when disabled. |
| 18            | OUT3        | Output      | Buffered output. Outputs tri-state with weak pull-down when disabled. |
| 19            | OUT2        | Output      | Buffered output. Outputs tri-state with weak pull-down when disabled. |
| 20            | OUT1        | Output      | Buffered output. Outputs tri-state with weak pull-down when disabled. |
| 21            | VDD         | Power       | Connect to +1.8 V.  |
| 22            | GND         | Power       | Connect to ground.  |
| 23            | TCXO_INA    | Input       | Connect to 13 MHz TCXO input.   |
| 24            | VDD         | Power       | Connect to +1.8 V.  |

## General I<sup>2</sup>C Serial Interface

### **How to Write:**

- Controller (host) sends a start bit
- Controller (host) sends the write address D2<sub>(H)</sub>
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location =N
- IDT clock will acknowledge
- Controller (host) sends the data byte count = X
- IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N + X 1 (see Note 2)
- IDT clock will acknowledge each byte one at a time
- · Controller (host) sends a Stop bit

| Index Block Write Operation |                         |                      |     |  |  |
|-----------------------------|-------------------------|----------------------|-----|--|--|
| Control                     | ler (Host)              | IDT (Slave/Receiver) |     |  |  |
| Т                           | starTbit                |                      |     |  |  |
| Slave Ad                    | dress D2 <sub>(H)</sub> |                      |     |  |  |
| WR                          | WRite                   |                      |     |  |  |
|                             |                         |                      | ACK |  |  |
| Beginnin                    | g Byte = N              |                      |     |  |  |
|                             |                         |                      | ACK |  |  |
| Data Byte                   | e Count = X             |                      |     |  |  |
|                             |                         |                      | ACK |  |  |
| Beginnin                    | g Byte = N              |                      |     |  |  |
|                             |                         | - <sub>X</sub>       | ACK |  |  |
|                             | 0                       | _ ^<br>_ B           |     |  |  |
|                             | 0                       | Υ                    | 0   |  |  |
|                             | 0                       | T<br>E               | 0   |  |  |
|                             |                         | 0                    |     |  |  |
| Byte N                      | N + X - 1               |                      |     |  |  |
|                             |                         |                      | ACK |  |  |
| Р                           | stoP bit                |                      |     |  |  |

### How to Read:

- · Controller (host) sends a start bit
- Controller (host) sends the write address D2<sub>(H)</sub>
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location =N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- Controller (host) sends the read address D3(H)
- IDT clock will acknowledge
- Controller (host) sends the data byte count = X
- IDT clock sends Byte N + X 1
- IDT clock sends Byte 0 through byte X (if X<sub>(H)</sub> was written to byte 8)
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

|      | Index Block Read Operation  |                      |                     |  |  |  |  |
|------|-----------------------------|----------------------|---------------------|--|--|--|--|
| Co   | ntroller (Host)             | IDT (Slave/Receiver) |                     |  |  |  |  |
| Т    | starTbit                    |                      |                     |  |  |  |  |
| Slav | e Address D2 <sub>(H)</sub> |                      |                     |  |  |  |  |
| WR   | WRite                       |                      |                     |  |  |  |  |
|      |                             |                      | ACK                 |  |  |  |  |
| Beg  | inning Byte = N             |                      |                     |  |  |  |  |
|      |                             |                      | ACK                 |  |  |  |  |
| RT   | Repeat starT                |                      |                     |  |  |  |  |
| Slav | e Address D3 <sub>(H)</sub> |                      |                     |  |  |  |  |
| RD   | ReaD                        |                      |                     |  |  |  |  |
|      |                             |                      | ACK                 |  |  |  |  |
|      |                             |                      |                     |  |  |  |  |
|      |                             |                      | Data Byte Count = X |  |  |  |  |
|      | ACK                         |                      |                     |  |  |  |  |
|      |                             | ] .                  | Beginning Byte N    |  |  |  |  |
|      | ACK                         | V                    |                     |  |  |  |  |
|      |                             | X<br>B               | 0                   |  |  |  |  |
| 0    |                             |                      | 0                   |  |  |  |  |
| 0    |                             |                      | 0                   |  |  |  |  |
| 0    |                             |                      |                     |  |  |  |  |
|      |                             |                      | Byte N + X - 1      |  |  |  |  |
| N    | Not acknowledge             |                      |                     |  |  |  |  |
| Р    | stoP bit                    |                      |                     |  |  |  |  |

# I<sup>2</sup>C Address

The IDT6P30006A is a slave-only device that supports block read and block write protocol using a single 7 bit address and read/write bit. A block write  $(D2_{(H)})$  or block read  $(D3_{(H)})$  is made up of seven (7) bits and one (1) read/write bit.

| <b>A</b> 6 | <b>A</b> 5 | <b>A</b> 4 | А3 | A2 | <b>A</b> 1 | Α0 | R/W# |
|------------|------------|------------|----|----|------------|----|------|
| 1          | 1          | 0          | 1  | 0  | 0          | 1  | Χ    |

In applications where the indexed block write and block read are used, the dummy byte (bit 11-18) functions as a register-offset (8 bits) pointer.

## **Byte 0: Control Register**

| Bit | Description         | Туре | Power Up<br>Condition | Output(s) Affected    | Notes                   |
|-----|---------------------|------|-----------------------|-----------------------|-------------------------|
| 7   | Reserved            | RW   | Undefined             | Not applicable        |                         |
| 6   | Reserved            | RW   | Undefined             | Not applicable        |                         |
| 5   | Reserved            | RW   | Undefined             | Not applicable        |                         |
| 4   | Reserved            | RW   | Undefined             | Not applicable        |                         |
| 3   | OE for clock output | RW   | 1                     | Output_5 clock output | 1=enabled<br>0=disabled |
| 2   | OE for clock output | RW   | 1                     | Output_6 clock output | 1=enabled<br>0=disabled |
| 1   | OE for clock output | RW   | 1                     | Output_7 clock output | 1=enabled<br>0=disabled |
| 0   | OE for clock output | RW   | 1                     | Output_8 clock output | 1=enabled<br>0=disabled |

# **Byte 1: Control Register**

| Bit    | Description | Туре | Power Up<br>Condition | Output(s) Affected | Notes |
|--------|-------------|------|-----------------------|--------------------|-------|
| 7 to 0 | Reserved    | RW   | Undefined             | Not applicable     |       |

# **Byte 2: Control Register**

| Bit    | Description | Туре | Power Up<br>Condition | Output(s) Affected | Notes |
|--------|-------------|------|-----------------------|--------------------|-------|
| 7 to 0 | Reserved    | RW   | Undefined             | Not applicable     |       |

# **Byte 3: Control Register**

| Bit    | Description | Туре | Power Up<br>Condition | Output(s) Affected | Notes |
|--------|-------------|------|-----------------------|--------------------|-------|
| 7 to 0 | Reserved    | RW   | Undefined             | Not applicable     |       |

# Byte 4 through 5: Control Register

| Bit    | Description | Туре | Power Up<br>Condition | Output(s) Affected | Notes |
|--------|-------------|------|-----------------------|--------------------|-------|
| 7 to 0 | Reserved    | RW   | Undefined             | Not applicable     |       |

# **Byte 6: Control Register**

| Bit | Description       | Туре | Power Up | Output(s) Affected | Notes |
|-----|-------------------|------|----------|--------------------|-------|
| 7   | Revision ID bit 3 | RW   | 0        | Not applicable     |       |
| 6   | Revision ID bit 2 | RW   | 0        | Not applicable     |       |
| 5   | Revision ID bit 1 | RW   | 0        | Not applicable     |       |
| 4   | Revision ID bit 0 | RW   | 0        | Not applicable     |       |
| 3   | Vendor ID bit 3   | RW   | 0        | Not applicable     |       |
| 2   | Vendor ID bit 2   | RW   | 0        | Not applicable     |       |
| 1   | Vendor ID bit 1   | RW   | 0        | Not applicable     |       |
| 0   | Vendor ID bit 0   | RW   | 1        | Not applicable     |       |

## **Applications Information**

### **External Components**

A minimum number of external components are required for proper operation.

### **Decoupling Capacitors**

Decoupling capacitors of 0.01  $\mu F$  should be connected between VDD and GND as close to the device as possible. Do not share ground vias between components. Route power from power source through the capacitor pad and then into IDT pin.

#### **PCB Layout Recommendations**

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

- 1. Each  $0.01\mu F$  decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible.
- 2. No vias should be used between decoupling capacitor and VDD pin.
- 3. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via. Distance of the ferrite bead and bulk decoupling from the device is less critical.
- 4. An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers (any ferrite beads and bulk decoupling capacitors can be mounted on the back). Other signal traces should be routed away from the IDT6P30006A. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

## **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the IDT6P30006A. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| Item                              | Rating              |
|-----------------------------------|---------------------|
| Max Supply Voltage, VDD           | 5 V                 |
| LVCMOS_INB, SCLK and SDATA Inputs | -0.5 V to +3.3 V    |
| All Other Inputs and Outputs      | -0.5 V to VDD+0.5 V |
| Ambient Operating Temperature     | -40 to +85° C       |
| Storage Temperature               | -65 to +150° C      |
| Junction Temperature              | 125° C              |
| Peak Soldering Temperature        | 260° C              |

## **Recommended Operation Conditions**

| Parameter   | Min. | Тур. | Max. | Units |
|---|------|------|------|-------|
| Ambient Operating Temperature                     | -40  |      | +85  | °C    |
| Power Supply Voltage (measured in respect to GND) | 1.62 | +1.8 | 1.98 | V     |

### **DC Electrical Characteristics**

Unless otherwise specified, VDD=1.8 V ±10%, Ambient Temperature -40 to +85° C

| Parameter                   | Symbol          | Conditions                               | Min.     | Тур. | Max.     | Units |
|-----------------------------|-----------------|--|----------|------|----------|-------|
| Operating Supply Voltage    | VDD             |  | 1.62     | 1.8  | 1.98     | V     |
| Input High Voltage          | V <sub>IH</sub> | SEL, OE pins, LVCMOS_INB, TCXO_INA       | 0.75xVDD |      |          | V     |
|                             |                 | SCLK and SDATA                           | 0.7xVDD  |      |          |       |
| Input Low Voltage           | V <sub>IL</sub> | SEL, OE pins, LVCMOS_INB, TCXO_INA       |          |      | 0.35xVDD | V     |
|                             |                 | SCLK and SDATA                           |          |      | 0.3xVDD  |       |
| High-Level Output Voltage   | V <sub>OH</sub> | I <sub>OH</sub> = -4 mA                  | VDD-0.4  |      |          | V     |
| Low-Level Output Voltage    | V <sub>OL</sub> | I <sub>OL</sub> = 4 mA                   |          |      | 0.4      | V     |
| Operating Supply Current    | IDD             | No load, all outputs switching at 13 MHz |          | 4    | 6        | mA    |
|                             |                 | All outputs disabled                     |          | 500  |          | μΑ    |
| Short Circuit Current       | Ios             | Single-ended clocks                      |          | ±70  |          | mA    |
| Output Impedance            | Z <sub>O</sub>  | All clock outputs, OEx=1                 |          | 15   |          | Ω     |
| Internal Pull-Up Resistor   | R <sub>PU</sub> | SEL, OEx                                 |          | 500  |          | kΩ    |
| Internal Pull-Down Resistor | R <sub>PD</sub> | All clock outputs, OEx=0                 |          | 250  |          | kΩ    |
| Input Capacitance           | C <sub>IN</sub> | All input pins                           |          | 6    |          | pF    |

# **AC Electrical Characteristics – Single-Ended Outputs**

Unless otherwise stated, **VDD = 1.8 V \pm10%**, Ambient Temperature -40 to +85° C

| Parameter                              | Symbol          | Conditions                                    | Min. | Тур. | Max. | Units |
|--|-----------------|---|------|------|------|-------|
| Input Frequency                        | F <sub>IN</sub> |   | 12.6 | 13   | 13.4 | MHz   |
| TCXO Input Swing                       |                 |   | ±100 |      | ±900 | mV    |
| Variance Input Frequencies             |                 | LVCMOS_INB, TCXO_INA,<br>Note 2               |      |      | 0.4  | MHz   |
| Time Switch Clock Inputs               |                 | LVCMOS_INB, TCXO_INA,<br>Note 3               |      | 80   |      | μs    |
| Output Frequency Error                 |                 |   |      | 0    |      | ppm   |
| Output Rise Time                       | t <sub>OR</sub> | 20% to 80%, Note 1                            |      | 1    | 1.5  | ns    |
| Output Fall Time                       | t <sub>OF</sub> | 80% to 20%, Note 1                            |      | 1    | 1.5  | ns    |
| Output Clock Duty Cycle                |                 | Measured at VDD/2, Note 1                     | 45   | 50   | 55   | %     |
| Clock Stabilization Time from Power Up |                 | Power up, output within 1% of final frequency |      | 3    | 10   | ms    |

Note 1: CL = 5 pF.

Note 2: Delta from 13 MHz.

Note 3: By removing primary input and then bringing back primary input.

### **Thermal Characteristics**

| Parameter                           | Symbol        | Conditions       | Min. | Тур. | Max. | Units |
|-------------------------------------|---------------|------------------|------|------|------|-------|
| Thermal Resistance Junction to      | $\theta_{JA}$ | Still air        |      | 29.1 |      | ° C/W |
| Ambient                             | $\theta_{JA}$ | 1 m/s air flow   |      | 22.8 |      | ° C/W |
|                                     | $\theta_{JA}$ | 2.5 m/s air flow |      | 21.0 |      | ° C/W |
| Thermal Resistance Junction to Case | $\theta_{JC}$ |                  |      | 41.8 |      | ° C/W |

# **Marking Diagram**

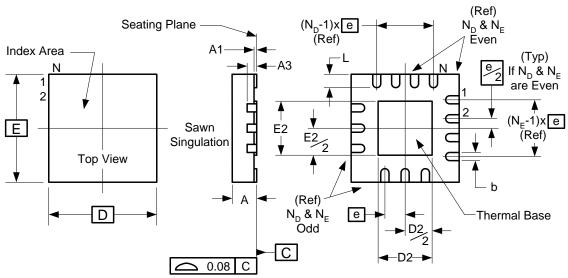


#### Notes:

- 1. YYWW is the last two digits of the year and week that the part was assembled.
- 3. "\$" is the assembly mark code.
- 4. "G" after the two-letter package code designates RoHS compliant package.
- 5. "I" at the end of part number indicates industrial temperature range.
- 6. Bottom marking: country of origin if not USA.

### Package Outline and Package Dimensions (24-pin QFN)

Package dimensions are kept current with JEDEC Publication No. 95



|                | Millimeters |          |  |  |  |
|----------------|-------------|----------|--|--|--|
| Symbol         | Min         | Max      |  |  |  |
| Α              | 0.80        | 1.00     |  |  |  |
| A1             | 0           | 0.05     |  |  |  |
| A3             | 0.25 Re     | eference |  |  |  |
| b              | 0.18        | 0.30     |  |  |  |
| е              | 0.50 BASIC  |          |  |  |  |
| N              | 24          |          |  |  |  |
| N <sub>D</sub> | 6           |          |  |  |  |
| N <sub>E</sub> | 6           |          |  |  |  |
| D x E BASIC    | 4.00 x 4.00 |          |  |  |  |
| D2             | 2.3         | 2.55     |  |  |  |
| E2             | 2.3         | 2.55     |  |  |  |
| L              | 0.30        | 0.50     |  |  |  |

## **Ordering Information**

| Part / Order Number | Marking    | Shipping Packaging | Package    | Temperature   |
|---------------------|------------|--------------------|------------|---------------|
| 6P30006ANLGI        | see pg. 10 | Trays              | 24-pin QFN | -40 to +85° C |
| 6P30006ANLGI8       |            | Tape and Reel      | 24-pin QFN | -40 to +85° C |

#### "G" after the two-letter package code are the Pb-Free configuration and are RoHS compliant.

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IDT6P30006A CLOCK DISTRIBUTION CIRCUIT

**DISTRIBUTION CIRCUITS** 

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